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Keiron Advances Digital Solder Printing Adoption with New England Expansion Through Yankee Soldering Technology

Eindhoven, Netherlands — February 2026 — Keiron Printing Technologies, a global innovator in advanced electronics manufacturing solutions, has appointed Yankee Soldering Technology as its authorized sales representative for the New England region. The partnership covers Connecticut, Rhode Island, Maine, Massachusetts, New Hampshire, and Vermont, and will support the regional introduction and adoption of Keiron's LiFT (Laser-Induced Forward Transfer) technology, including the company's latest system, the Keiron HF2 LiFT Printer.

Yankee Soldering Technology is a sales organization dedicated to helping New England manufacturers compete on a global scale. With strong regional relationships and a technical, process-driven approach aligned with high-performance SMT environments, Yankee Soldering will represent Keiron's LiFT platform to manufacturers seeking greater control, flexibility, and consistency in solder paste deposition.

Keiron's LiFT technology replaces traditional stencil- and nozzle-based solder paste deposition with a laser-driven, non-contact digital process. By eliminating stencils, nozzles, ejectors, and other mechanical contact points, LiFT removes a major source of process variability while directly addressing one of the most common contributors to assembly defects: inconsistent solder paste application.

The Keiron HF2 LiFT Printer enables precise, repeatable solder paste deposition down to nanoliter volumes while working with standard solder pastes and accepting common CAD, Gerber, and ODB++ file formats. This allows manufacturers to implement digital solder paste printing without changing materials or disrupting established workflows. With no stencils to fabricate, clean, or store, changeovers can be completed in minutes, making the HF2 particularly well suited for high-mix, low-volume, and NPI-focused production.

A key differentiator of the HF2 is its integrated Solder Paste Volume Metrology (SPVM), which measures every deposit in real time during the printing process. This built-in verification improves first-pass yield and reduces rework and scrap without requiring a separate SPI system. The contactless



Andrew Rollins, Yankee Soldering

architecture also avoids common reliability challenges such as clogging, mechanical wear, and alignment drift associated with conventional printing methods.

“Yankee Soldering brings deep regional knowledge and a strong technical mindset that aligns well with how LiFT technology is deployed on the factory floor,” said Brian Duffey, President of Keiron Technologies USA. “Their experience supporting high-mix and advanced SMT operations makes them an excellent partner as we expand LiFT adoption across New England.”

For more information about Yankee Soldering Technology, visit www.yankeesoldering.com.

For more information about Keiron’s industry revolutionizing technology, visit www.keirontechnologies.com.

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About Keiron Printing Technologies

Keiron Printing Technologies is a global innovator in advanced electronics manufacturing equipment, specializing in fully digital, LiFT-based precision solder paste printing solutions. Designed for modern, high-performance production environments, Keiron’s technology enables zero-waste, high-accuracy manufacturing while supporting rapid innovation and sustainable growth.